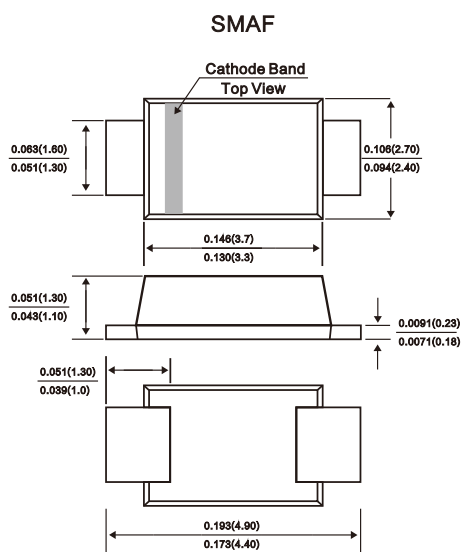


### Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

### MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg / 0.00095oz



Dimensions in inches and (millimeters)

### Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS32F	SS34 F	SS36F	SS38F	SS310F	SS312F	SS315F	SS320F	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	$V_{RMS}$	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	$V_{DC}$	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	80				70				A
Max Instantaneous Forward Voltage at 3 A	$V_F$	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Reverse Voltage $T_a = 100^\circ\text{C}$	$I_R$	0.5 5			0.3 3				mA	
Typical Junction Capacitance <sup>(1)</sup>	$C_j$	250			180				pF	
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$	70								°C/W
Operating Junction Temperature Range	$T_j$	-55 ~ +150								°C
Storage Temperature Range	$T_{stg}$	-55 ~ +150								°C

( 1 ) Measured at 1 MHz and applied reverse voltage of 4 V D.C

( 2 ) P.C.B. mounted with 2.0" X 2.0" ( 5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

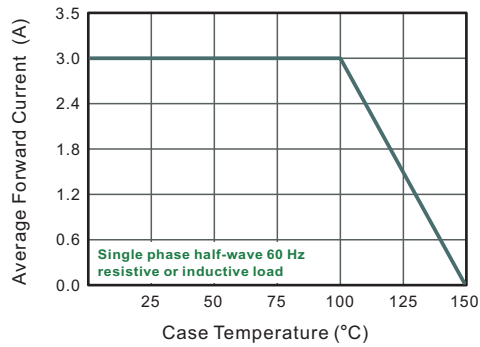


Fig.2 Typical Reverse Characteristics

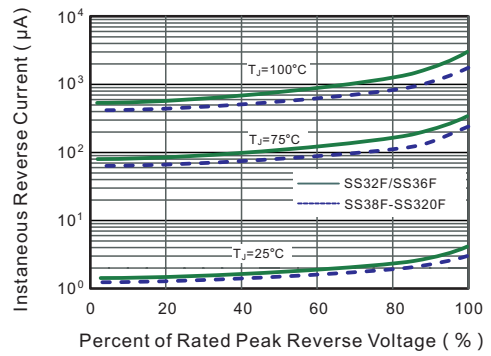


Fig.3 Typical Forward Characteristic

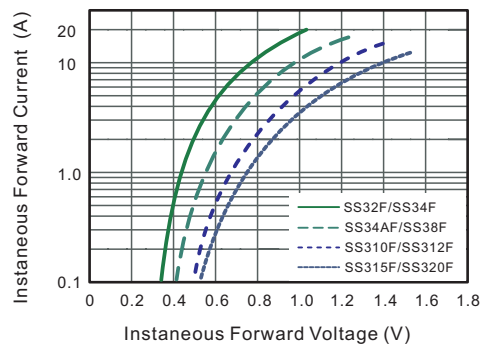


Fig.4 Typical Junction Capacitance

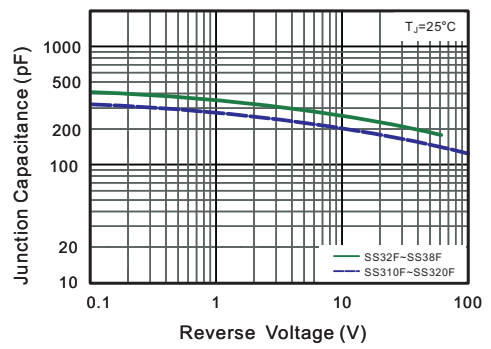


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

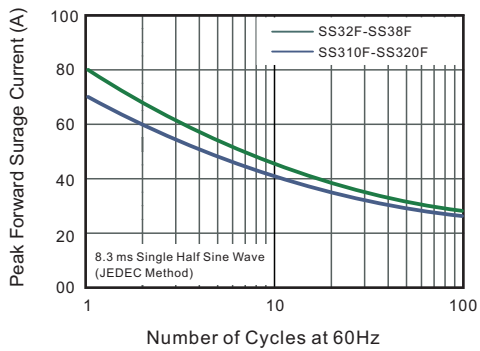
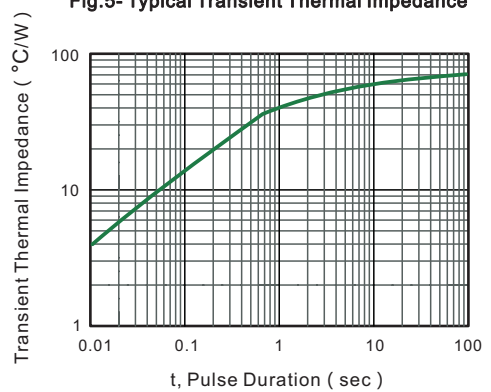


Fig.5- Typical Transient Thermal Impedance



单击下面可查看定价，库存，交付和生命周期等信息

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